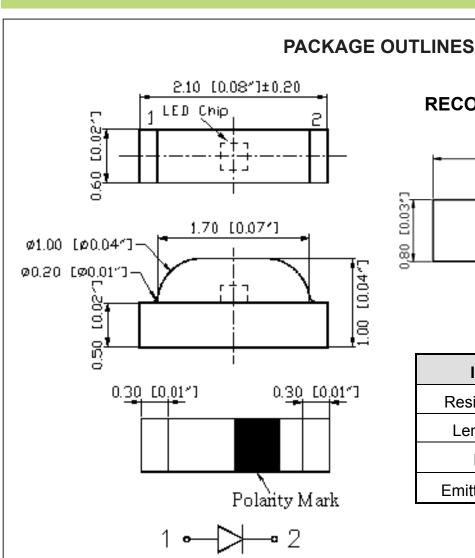
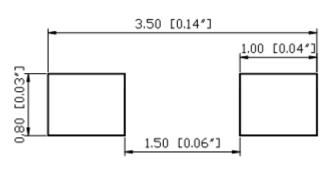


SPECIFICATION CSR84G1C



RECOMMEND PAD LAYOUT



ITEM MATERIALS			
Resin (mold)	Ероху		
Lens color	Water Transparent		
Dice	GaP/GaP		
Emitted Color	Yellow Green		

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CSR84G1C	GaP	Green	Water Clear	150°	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit		
Forward Current	lF	30	mA		
Reverse Current @ 5V	Pd		μΑ		
Power Dissipation			mW		
Operating Temperature Range	Тор	-40~+80	°C		
Storage Temperature Range	Тѕтс	-40~+85	°C		
Peak Pulsing Current (1/10 duty f = 10KHz)	lfP	125	mA		
Soldering Temperature	TsoL	Max 260°C for	5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Parameter	Symbol	Test Condition	Value			l lait
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	5	15	ı	mcd
Forward Voltage	VF	IF = 20mA	ı	2.0	2.5	V
Reverse Leakage Current	lR	V _R = 5V	1	ı	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	ı	150	ı	Deg
Peak Wavelength	λ P	IF = 20mA	1	565		nm
Dominant Wavelength	λ D	IF = 20mA	1	570	ı	nm

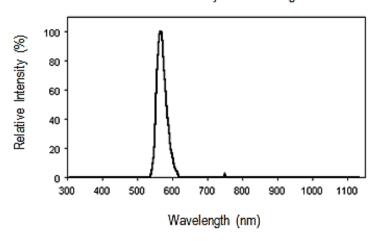
^{*}Tolerance of viewing angle: -10 / +5 deg.



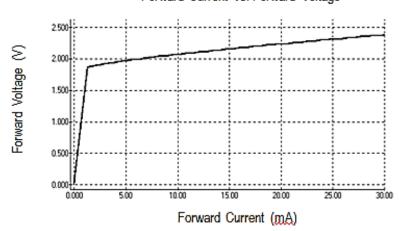


OPTICAL CHARACTERISTIC CURVES

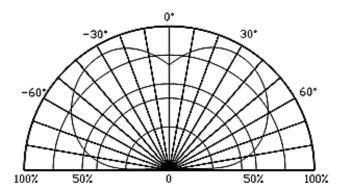
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics

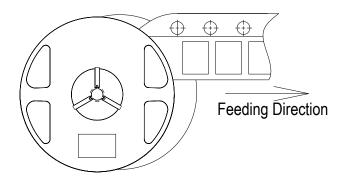




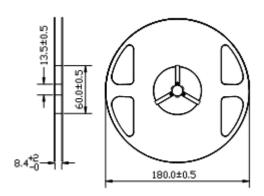


PACKAGING SPECIFICATION

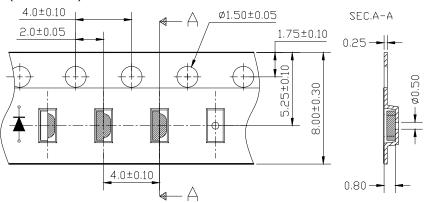
Feeding Direction



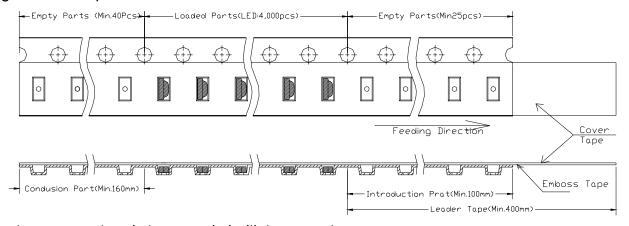
Dimensions of Reel (Unit: mm)



Dimensions of Tape (Unit: mm)



Arrangement of Tape



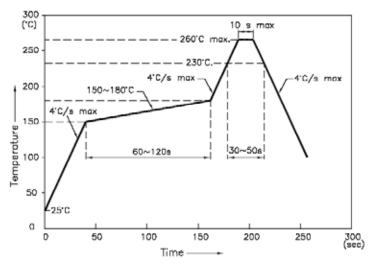
- Empty component pockets are sealed with top cover tape
- The maximum number of missing lamps is two
- The cathode is oriented towards the tape sprocket hole





SOLDERING CONDITIONS

REFLOW PROFILE



- 1. We recommend the reflow temperature 245°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Do not cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.

Soldering Iron

Basic spec is ≤5sec when 260°C. If temperature is higher, time should be shorter (+10°C→-1sec). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230°C.

Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron cannot touch copper foil.
- 3. Twin-head type is preferred.

